

Specifications

Insulation Resistance:	1,000M Ω min. at 500V DC
Dielectric Withstanding Voltage:	700V AC for 1 minute
Contact Resistance:	30m Ω max. at 10mA/20mV max.
Operating Temperature Range:	-55°C to +170°C
Mating Cycles:	10,000 insertions minimum
Pin Count:	184 contact pins

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
Contacts: Beryllium Copper (BeCu)
Plating: Gold over Nickel

Features

- Card thickness 1.27mm
- For 184 contact pins with 1.00mm pitch



Part Number (Details)

IC-595 - * - MF

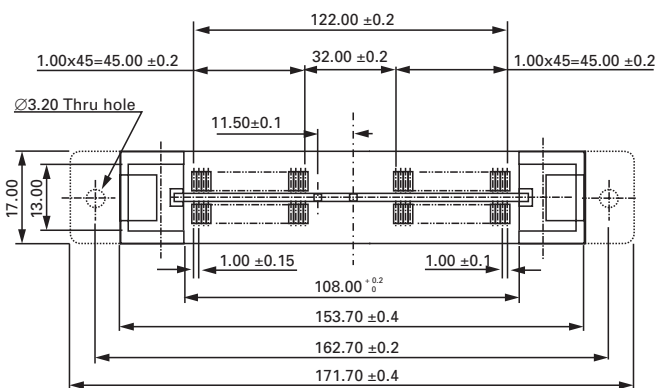
Series No.

1 = 184 Pins

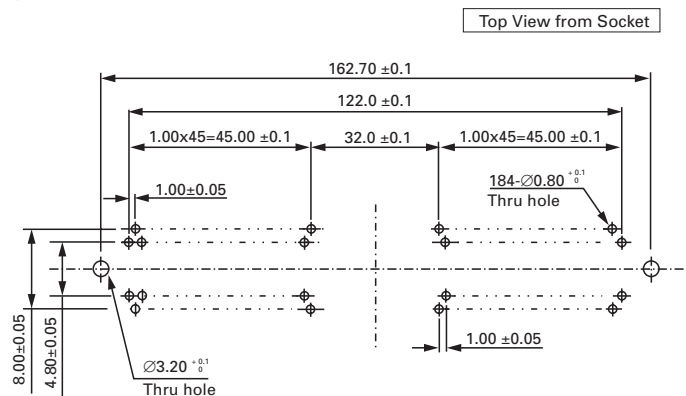
2 = 240 Pins

MF = Flanged
Unmarked = Not Flanged

Outline Socket Dimensions



Recommended PC Board Layout



Matching Module Dimensions

